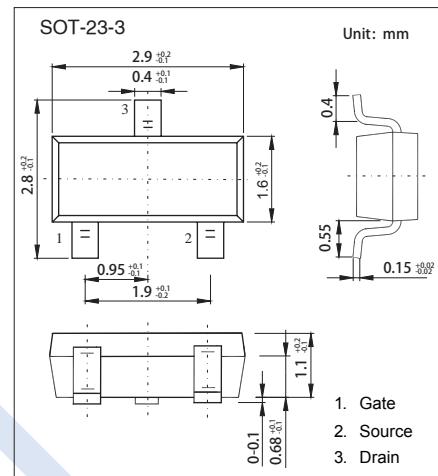
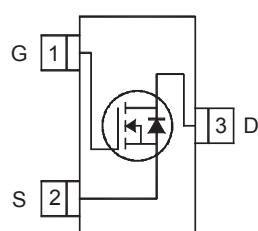


## N-Channel MOSFET

2KK5037

## ■ Features

- $V_{DS} (V) = 110V$
- $I_D = 3.0A$  ( $V_{GS} = 10V$ )
- $R_{DS(ON)} \leq 180m\Omega$  ( $V_{GS} = 10V$ )
- $R_{DS(ON)} \leq 240m\Omega$  ( $V_{GS} = 4.5V$ )

■ Absolute Maximum Ratings  $T_a = 25^\circ C$ 

| Parameter  | Symbol     | Rating     | Unit |
|--|------------|------------|------|
| Drain-Source Voltage                             | $V_{DS}$   | 110        | V    |
| Gate-Source Voltage                              | $V_{GS}$   | $\pm 20$   |      |
| Continuous Drain Current @ $V_{GS}=10V$          | $I_D$      | 3.0        | A    |
|  |            | 2.4        |      |
| Pulsed Drain Current                             | $I_{DM}$   | 10         |      |
| Power Dissipation                                | $P_D$      | 1.25       | W    |
|  |            | 0.8        |      |
| Thermal Resistance.Junction- to-Ambient (Note.1) | $R_{thJA}$ | 100        | °C/W |
| Junction Temperature                             | $T_J$      | 150        | °C   |
| Storage Temperature Range                        | $T_{stg}$  | -55 to 150 |      |

Note.1: Surface mounted on 1 in square Cu board

## N-Channel MOSFET

## 2KK5037

■ Electrical Characteristics ( $T_J = 25^\circ\text{C}$  unless otherwise specified)

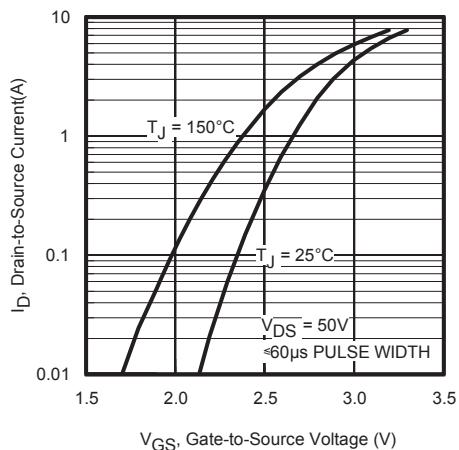
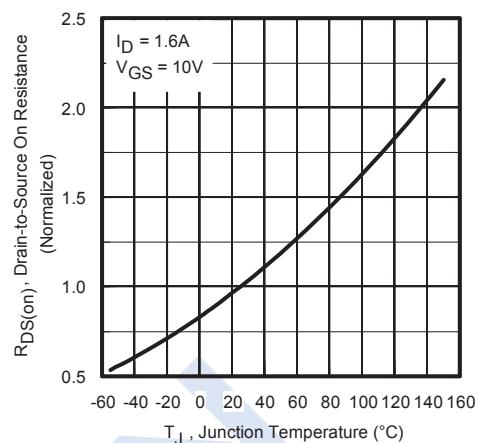
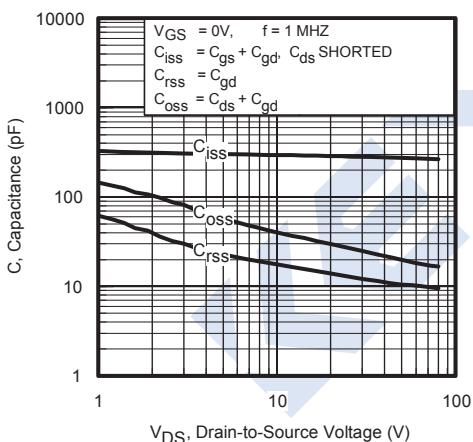
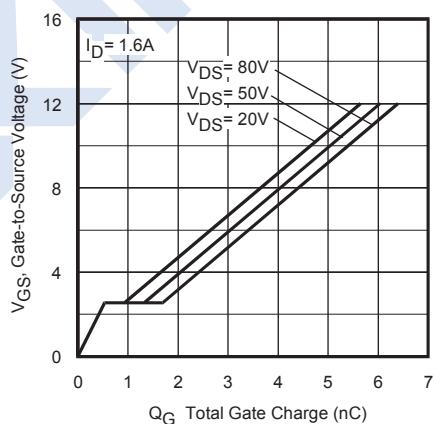
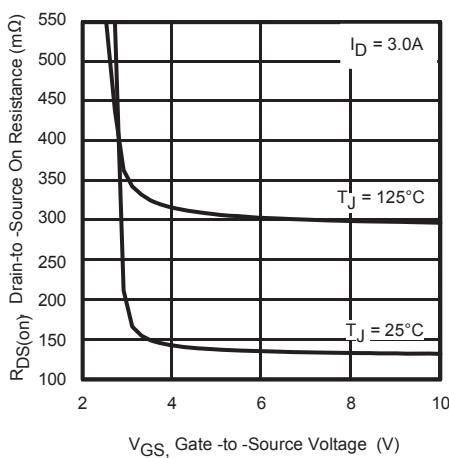
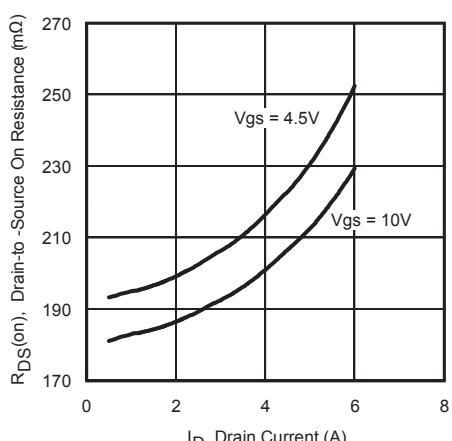
| Parameter                                  | Symbol       | Test Conditions   | Min | Typ | Max       | Unit             |
|--|--------------|---|-----|-----|-----------|------------------|
| Drain-Source Breakdown Voltage             | $V_{DSS}$    | $I_D=250 \mu\text{A}, V_{GS}=0\text{V}$   | 110 |     |           | V                |
| Zero Gate Voltage Drain Current            | $I_{DS(on)}$ | $V_{DS}=110\text{V}, V_{GS}=0\text{V}$  |     |     | 1         | $\mu\text{A}$    |
|  |              | $V_{DS}=110\text{V}, V_{GS}=0\text{V}, T_J=125^\circ\text{C}$                                       |     |     | 150       |                  |
| Gate-Body Leakage Current                  | $I_{GSS}$    | $V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$   |     |     | $\pm 100$ | nA               |
| Gate Threshold Voltage                     | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250 \mu\text{A}$  | 1   |     | 3.0       | V                |
| Static Drain-Source On-Resistance (Note.1) | $R_{DS(on)}$ | $V_{GS}=4.5\text{V}, I_D=1.0\text{A}$   |     |     | 240       | $\text{m}\Omega$ |
|  |              | $V_{GS}=10\text{V}, I_D=3.0\text{A}$  |     |     | 180       |                  |
| Forward Transconductance                   | $g_{FS}$     | $V_{DS}=5\text{V}, I_D=3.0\text{A}$   | 5.7 |     |           | S                |
| Input Capacitance                          | $C_{iss}$    | $V_{GS}=0\text{V}, V_{DS}=25\text{V}, f=1\text{MHz}$  |     | 290 |           | $\text{pF}$      |
| Output Capacitance                         | $C_{oss}$    |   |     | 27  |           |                  |
| Reverse Transfer Capacitance               | $C_{rss}$    |   |     | 13  |           |                  |
| Gate Resistance                            | $R_g$        |   |     | 1.3 |           | $\Omega$         |
| Total Gate Charge                          | $Q_g$        | $V_{GS}=4.5\text{V}, V_{DS}=50\text{V}, I_D=3.0\text{A}$  |     | 2.5 |           | $\text{nC}$      |
| Gate Source Charge                         | $Q_{gs}$     |   |     | 0.5 |           |                  |
| Gate Drain Charge                          | $Q_{gd}$     |   |     | 1.2 |           |                  |
| Turn-On Delay Time                         | $t_{d(on)}$  | $V_{GS}=4.5\text{V}, V_{DS}=50\text{V}, I_D=1\text{A}, R_{GEN}=6.8 \Omega$                          |     | 2.2 |           | $\text{ns}$      |
| Turn-On Rise Time                          | $t_r$        |   |     | 2.1 |           |                  |
| Turn-Off Delay Time                        | $t_{d(off)}$ |   |     | 9   |           |                  |
| Turn-Off Fall Time                         | $t_f$        |   |     | 3.6 |           |                  |
| Body Diode Reverse Recovery Time           | $t_{rr}$     | $V_R=50\text{V}, I_F= 1.1\text{A}, dI/dt= 100\text{A}/\mu\text{s}, T_J = 25^\circ\text{C}$ (Note.1) |     | 20  | 30        | $\text{nC}$      |
| Body Diode Reverse Recovery Charge         | $Q_{rr}$     |   |     | 13  | 20        |                  |
| Maximum Body-Diode Continuous Current      | $I_s$        |   |     |     | 2.0       | $\text{A}$       |
| Pulsed Source Current                      | $I_{SM}$     | (Note.2)  |     |     | 10        |                  |
| Diode Forward Voltage                      | $V_{SD}$     | $I_s=3.0\text{A}, V_{GS}=0\text{V}, T_J = 25^\circ\text{C}$ (Note.1)                                |     |     | 1.3       | V                |

Note.1: Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

Note.2: Repetitive rating; pulse width limited by max. junction temperature.

## ■ Marking

|         |      |
|---------|------|
| Marking | KBK* |
|---------|------|

**N-Channel MOSFET****2KK5037****■ Typical Characteristics****Fig 1.** Typical Transfer Characteristics**Fig 2.** Normalized On-Resistance Vs. Temperature**Fig 3.** Typical Capacitance Vs. Drain-to-Source Voltage**Fig 4.** Typical Gate Charge Vs. Gate-to-Source Voltage**Fig 5.** Typical On-Resistance Vs. Gate Voltage**Fig 6.** Typical On-Resistance Vs. Drain Current